



Dual P-Channel 12-V (D-S) MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	
- 12	0.015 at V _{GS} = - 4.5 V	- 12.8	
	0.019 at V _{GS} = - 2.5 V	- 11.4	
	0.024 at V _{GS} = - 1.8 V	- 10.1	

FEATURES

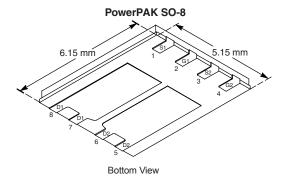
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET: 1.8 V Rated
- New Low Thermal Resistance PowerPAK[®] Package



ROHS COMPLIANT HALOGEN FREE

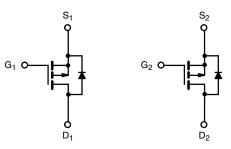
APPLICATIONS

Load Switch



Ordering Information: Si7973DP-T1-E3 (Lead (Pb)-free)

Si7973DP-T1-GE3 (Lead (Pb)-free and Halogen-free)



P-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise r	noted		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	- 12		V
Gate-Source Voltage		V _{GS}	± 8		
Continuous Drain Current (T _{.1} = 150 °C) ^a	T _A = 25 °C	I _D	- 12.8	- 8.2	А
Continuous Diain Current (1) = 150 C)	T _A = 70 °C		- 9.2	- 5.9	
Pulsed Drain Current		I _{DM}	- 30		A
Continuous Source Current (Diode Conduction) ^a		I _S	- 2.9	- 1.2	
Maximum Power Dissipation ^a	T _A = 25 °C	P _D	3.5	1.4	W
Maximum Fower Dissipation	T _A = 70 °C	' D	1.9	0.8	VV
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C
Soldering Recommendations (Peak Temperature)			:	260	C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian una lumation ta Amelianta	t ≤ 10 s	R _{thJA}	26	35	°C/W
Maximum Junction-to-Ambient ^a	Steady State		60	85	
Maximum Junction-to-Case (Drain)	Steady State	Rthuc	2.2	2.7	

Notes

a. Surface Mounted on 1" x 1" FR4 board.

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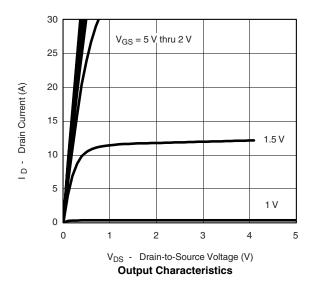


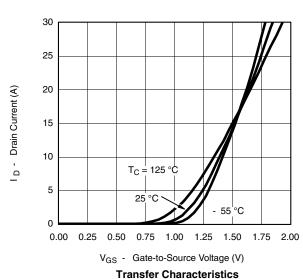
SPECIFICATIONS T _J = 25 °C, unless otherwise noted								
Parameter	Symbol	Test Conditions Min.		Тур.	Max.	Unit		
Static			•	•				
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -600 \mu A$	- 0.40		- 1.0	V		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA		
Zero Gate Voltage Drain Current	1	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}$			- 1			
Zero Gate voltage Drain Current	IDSS	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			- 5	μΑ		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 30			Α		
		$V_{GS} = -4.5 \text{ V}, I_D = -12.8 \text{ A}$		0.012	0.015			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 11.4 A		0.015	0.019			
	==(:)	V _{GS} = - 1.8 V, I _D = - 4.2 A		0.019	0.024			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -6 \text{ V}, I_{D} = -12.8 \text{ A}$		35		S		
Diode Forward Voltage ^a	V_{SD}	I _S = - 2.9 A, V _{GS} = 0 V		- 0.8	- 1.2	V		
Dynamic ^b								
Total Gate Charge	Q_g			55	80			
Gate-Source Charge	Q _{gs} V	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -12.8 \text{ A}$		8.1		nC		
Gate-Drain Charge	Q_{gd}			15.4				
Gate Resistance	R_g	f = 1 MHz		8		Ω		
Turn-On Delay Time	t _{d(on)}			40	60			
Rise Time	$V_{DD} = -6 \text{ V}, R_L = 6 \Omega$			72	110			
Turn-Off Delay Time	$t_{d(off)}$ $I_D \cong -1 A, V_{GEN} = -4.5 V, R_g = 6 \Omega$	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 6 Ω		360	540	ns		
Fall Time	t _f			260	390			
Source-Drain Reverse Recovery Time	t _{rr}	I _F = - 2.9 A, dl/dt = 100 A/μs		166	250			

- Notes a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



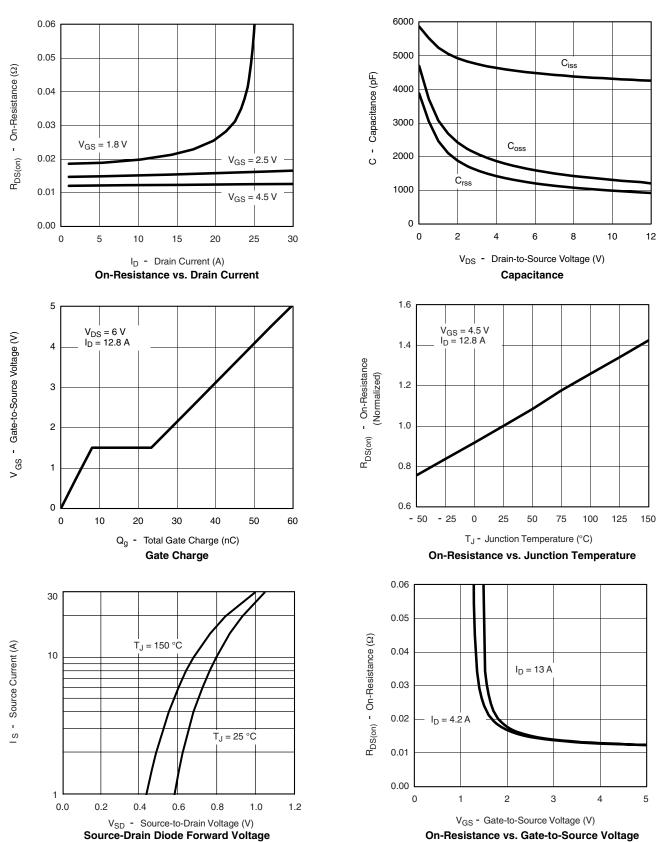








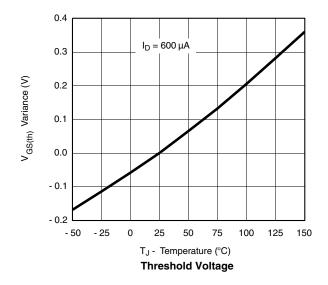
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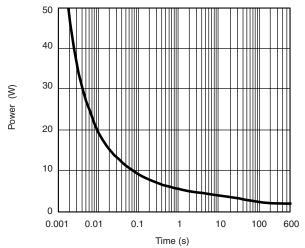


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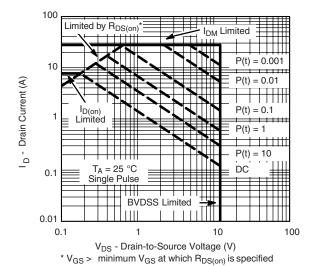
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

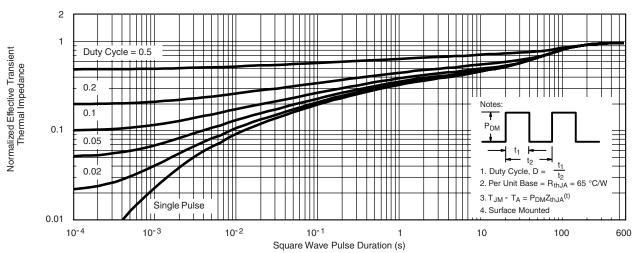




Single Pulse Power, Junction-to-Ambient



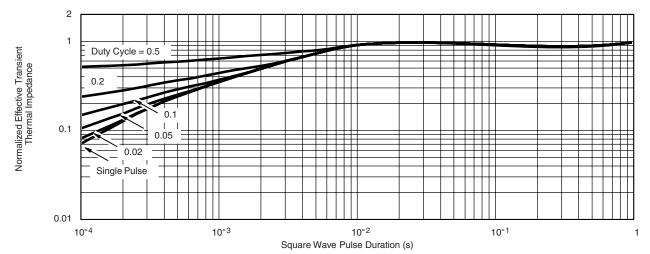
Safe Operating Area, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

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